

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Byung Tai Do</td><td>02/22/2008</td></tr><tr><td>Heap Hoe Kuan</td><td>02/22/2008</td></tr><tr><td>Yaojian Lin</td><td>02/22/2008</td></tr><tr><td>Rui Huang</td><td>02/22/2008</td></tr></tbody></table>	Name	Execution Date	Byung Tai Do	02/22/2008	Heap Hoe Kuan	02/22/2008	Yaojian Lin	02/22/2008	Rui Huang	02/22/2008	
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Byung Tai Do	02/22/2008										
Heap Hoe Kuan	02/22/2008										
Yaojian Lin	02/22/2008										
Rui Huang	02/22/2008										
RECEIVING PARTY DATA											
Name:	STATS ChipPAC, Ltd.										
Street Address:	10 Ang Mo Kio Street 65										
Internal Address:	#05-17/20 Techpoint										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	569059										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12036000</td></tr></tbody></table>	Property Type	Number	Application Number:	12036000							
Property Type	Number										
Application Number:	12036000										
CORRESPONDENCE DATA											
Fax Number:	(602)229-5690										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Correspondent Name:	Robert D. Atkins										
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Address Line 2:	TWO NORTH CENTRAL AVENUE										
Address Line 4:	PHOENIX, ARIZONA 85004-2391										
ATTORNEY DOCKET NUMBER:	125155.00094										
NAME OF SUBMITTER:	Robert D. Atkins										

CH \$40.00 12036000

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PATENT
REEL: 020548 FRAME: 0386

Total Attachments: 4

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ASSIGNMENT AND AGREEMENT

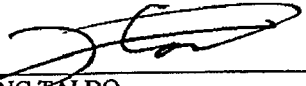
For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF SUPPORTING A WAFER DURING BACKGRINDING AND REFLOW OF SOLDER BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00094, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.



Signature for BYUNG TAI DO

Witnessed on this date:

22 Feb 2008

Signature of Witness:



Printed Name of Witness:

GOH HIN HWA

Address of Witness:

BLK 806 YISHUN ROAD RING ROAD
#06-4267, S'PORE 760806

QBACTIVE\6088779.1

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEAP HOE KUAN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF SUPPORTING A WAFER DURING BACKGRINDING AND REFLOW OF SOLDER BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00094, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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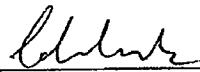


Signature for HEAP HOE KUAN

Witnessed on this date:

22 Feb 2008

Signature of Witness:



Printed Name of Witness:

GOO H HIN HWA

Address of Witness:

BLK 806, YISHUN RING ROAD
06-4267. S'PORE 760806

QBACTIVE\6088763.1

ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF SUPPORTING A WAFER DURING BACKGRINDING AND REFLOW OF SOLDER BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00094, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for YAOJIAN LIN

Witnessed on this date:

22 Feb 2008

Signature of Witness:



Printed Name of Witness:

GOH HIN HWA

Address of Witness:

BLK 806, YISHUN RING ROAD
#06-4267, S'PORE 760806

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ASSIGNMENT AND AGREEMENT

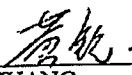
For good and valuable consideration, the receipt of which is hereby acknowledged, I, RUI HUANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF SUPPORTING A WAFER DURING BACKGRINDING AND REFLOW OF SOLDER BUMPS, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 125155.00094, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for RUI HUANG

Witnessed on this date: 22 Feb 2008

Signature of Witness: 

Printed Name of Witness: GOH HIN HWA

Address of Witness: Blk 806, YISHUN RING ROAD
#06-4267. S'PORE 760806

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